

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-55 (canceled)

56. (New) A method of manufacturing a semiconductor device comprising:

forming a first insulating film over a first substrate;

forming at least first and second thin film transistors over the first insulating film;

forming a second insulating film over the first and second thin film transistors;

forming a wiring and a first electrode over the second insulating film, wherein the wiring is connected to the first thin film transistor through a first contact hole in the second insulating film, and the first electrode is connected to the second thin film transistor through a second contact hole in the second insulating film;

forming a third insulating film over the second insulating film, the wiring, and the electrode;

forming a third contact hole for reaching the electrode in the third insulating film;

bonding a second substrate to a surface of the third insulating film; removing the first substrate;

forming a fourth contact hole for reaching the first thin film transistor in the first insulating film;

forming a second electrode on the first insulating film, wherein the second electrode is connected to the first thin film transistor through the fourth contact hole;

forming a fourth insulating film over the first insulating film and the second electrode; and

forming a fifth contact hole for reaching the second electrode in the fourth insulating film; and
removing the second substrate.

57. (New) A method according to claim 56, wherein the semiconductor device is incorporated into an electronic device selected from the group consisting: a cell phone, a video camera, a mobile computer, a goggle type display, a rear projector, and a front projector.

58. (New) A method according to claim 56, wherein the semiconductor device is an active matrix liquid crystal display device.

59. (New) A method according to claim 56, wherein the semiconductor device is an EL display device.

60. (New) A method according to claim 56, wherein in the step of bonding the second substrate to the surface of the third insulating film, the bonding is established by one or more bonding portions of a bonding layer.

61. (New) A method of manufacturing a semiconductor device comprising:

forming first and second thin film devices, the method of forming the first and second thin film devices, each comprising:

forming a first insulating film over a first substrate;

forming at least first and second thin film transistors over the first insulating film;

forming a second insulating film over the first and second thin film transistors;

forming a wiring and a first electrode over the second insulating film, wherein the wiring is connected to the first thin film transistor through a first contact hole in the second insulating film, and the first electrode is connected to the second thin film

transistor through a second contact hole in the second insulating film;

forming a third insulating film over the second insulating film, the wiring, and the electrode;

forming a third contact hole for reaching the electrode in the third insulating film;

bonding a second substrate to a surface of the third insulating film;

removing the first substrate;

forming a fourth contact hole for reaching the first thin film transistor in the first insulating film;

forming a second electrode on the first insulating film, wherein the second electrode is connected to the first thin film transistor through the fourth contact hole;

forming a fourth insulating film over the first insulating film and the second electrode; and

forming a fifth contact hole for reaching the second electrode in the fourth insulating film; and

removing the second substrate;

bonding the first thin film device to the second thin film device so that the fifth contact hole of the first thin film device is opposed to the third contact hole of the second thin film device,

wherein a conductive connection is made in the third and fifth contact holes opposed to each other.

62. (New) A method according to claim 61, wherein the semiconductor device is incorporated into an electronic device selected from the group consisting: a cell phone, a video camera, a mobile computer, a goggle type display, a rear projector, and a front projector.

63. (New) A method according to claim 61, wherein the semiconductor device is an active matrix liquid crystal display device.

64. (New) A method according to claim 61, wherein the semiconductor device is an EL display device.

65. (New) A method according to claim 61, wherein in the step of bonding the second substrate to the surface of the third insulating film, the bonding is established by one or more bonding portions of a bonding layer.

66. (New) A method according to claim 61, wherein a conductive paste is formed in the third and fifth contact holes.

67. (New) A method of manufacturing a semiconductor device comprising:

forming first, second, and third thin film devices, the method of forming the first, second, and third thin film devices, each comprising:

forming a first insulating film over a first substrate;

forming at least first and second thin film transistors over the first insulating film;

forming a second insulating film over the first and second thin film transistors;

forming a wiring and a first electrode over the second insulating film, wherein the wiring is connected to the first thin film transistor through a first contact hole in the second insulating film, and the first electrode is connected to the second thin film transistor through a second contact hole in the second insulating film;

forming a third insulating film over the second insulating film, the wiring, and the electrode;

forming a third contact hole for reaching the electrode in the third insulating film;

bonding a second substrate to a surface of the third insulating film;

removing the first substrate;
forming a fourth contact hole for reaching the first thin film transistor in the first insulating film;
forming a second electrode on the first insulating film, wherein the second electrode is connected to the first thin film transistor through the fourth contact hole;
forming a fourth insulating film over the first insulating film and the second electrode; and
forming a fifth contact hole for reaching the second electrode in the fourth insulating film; and
removing the second substrate;
bonding the first thin film device to the second thin film device so that the fifth contact hole of the first thin film device is opposed to the third contact hole of the second thin film device, and bonding the third thin film device to the second thin film device so that the third contact hole of the third thin film device is opposed to the fifth contact hole of the second thin film device,
wherein a conductive connection is made in the third and fifth contact holes opposed to each other.

68. (New) A method according to claim 67, wherein the semiconductor device is incorporated into an electronic device selected from the group consisting: a cell phone, a video camera, a mobile computer, a goggle type display, a rear projector, and a front projector.

69. (New) A method according to claim 67, wherein the semiconductor device is an active matrix liquid crystal display device.

70. (New) A method according to claim 67, wherein the semiconductor device is an EL display device.

71. (New) A method according to claim 67, wherein in the step of bonding the second substrate to the surface of the third insulating film, the bonding is established by one or more bonding portions of a bonding layer.

72. (New) A method according to claim 67, wherein a conductive paste is formed in the third and fifth contact holes.

73. (New) A semiconductor device comprising:

- a first thin film device; and

- a second thin film device on the first thin film device,

- each of the first and second thin film devices comprising:

- a first insulating film;

- a first electrode over the first insulating film;

- a second insulating film over the first electrode;

- first and second thin film transistors over the second insulating film,

wherein the first thin film transistor is connected to the first electrode through a first contact hole;

- a third insulating film over the first and second thin film transistor;

- a second electrode over the third insulating film, wherein the second electrode is connected to the second thin film transistor through a second contact hole;

- a fourth insulating film over the third insulating film and the second electrode,

wherein the second electrode of the first thin film device is electrically connected to the first electrode of the second thin film device.

74. (New) A semiconductor device according to claim 73, wherein the semiconductor device is incorporated into an electronic device selected from the group consisting: a cell

phone, a video camera, a mobile computer, a goggle type display, a rear projector, and a front projector.

75. (New) A semiconductor device according to claim 73, wherein the semiconductor device is an active matrix liquid crystal display device.

76. (New) A semiconductor device according to claim 73, wherein the semiconductor device is an EL display device.

77. (New) A semiconductor device comprising:

- a first thin film device;

- a second thin film device on the first thin film device; and

- a third thin film device on the second thin film device,

- each of the first, second, and third thin film devices comprising:

- a first insulating film;

- a first electrode over the first insulating film;

- a second insulating film over the first electrode;

- first and second thin film transistors over the second insulating film,

wherein the first thin film transistor is connected to the first electrode through a first contact hole;

- a third insulating film over the first and second thin film transistor;

- a second electrode over the third insulating film, wherein the second electrode is connected to the second thin film transistor through a second contact hole;

- a fourth insulating film over the third insulating film and the second electrode,

wherein the second electrode of the first thin film device is electrically connected to the first electrode of the second thin film device, and

wherein the second electrode of the second thin film device is electrically connected to the first electrode of the third thin film device.

78. (New) A method according to claim 77, wherein the semiconductor device is incorporated into an electronic device selected from the group consisting: a cell phone, a video camera, a mobile computer, a goggle type display, a rear projector, and a front projector.

79. (New) A method according to claim 77, wherein the semiconductor device is an active matrix liquid crystal display device.

80. (New) A method according to claim 77, wherein the semiconductor device is an EL display device.